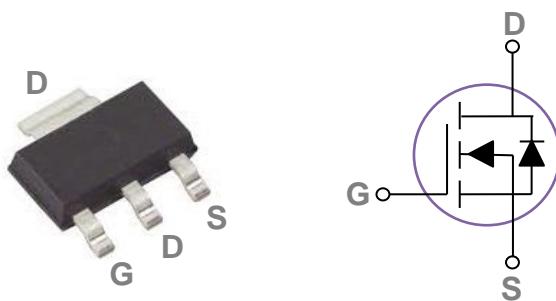


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOT223 Pin Configuration



BVDSS	RDS(ON)	ID
60V	60mΩ	6.8A

### Features

- 60V, 6.8A,  $RDS(ON) = 60m\Omega @ VGS = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Motor Drive
- Power Tools
- LED Lighting

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_A=25^\circ C$ )	6.8	A
	Drain Current – Continuous ( $T_A=70^\circ C$ )	5.4	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	27.2	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	11	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	15	A
$P_D$	Power Dissipation ( $T_A=25^\circ C$ )	3.6	W
	Power Dissipation – Derate above 25°C	0.03	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient ( $t \leq 10s$ )	---	35	°C/W
	Thermal Resistance Junction to ambient (Steady State)	---	70	°C/W

**Electrical Characteristics ( $T_J=25\text{ }^{\circ}\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	60	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25\text{ }^{\circ}\text{C}$ , $I_D=1\text{mA}$	---	0.05	---	$\text{V}/\text{C}$
$I_{DS}$	Drain-Source Leakage Current	$V_{DS}=60\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=125\text{ }^{\circ}\text{C}$	---	---	10	$\mu\text{A}$
$I_{GS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$ , $I_D=6\text{A}$	---	50	60	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=3\text{A}$	---	56	70	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	1.2	1.8	2.5	V
			---	-4.2	---	$\text{mV}/\text{C}$
$g_{fs}$	Forward Transconductance	$V_{DS}=10\text{V}$ , $I_D=4\text{A}$	---	10	---	S

**Dynamic and switching Characteristics**

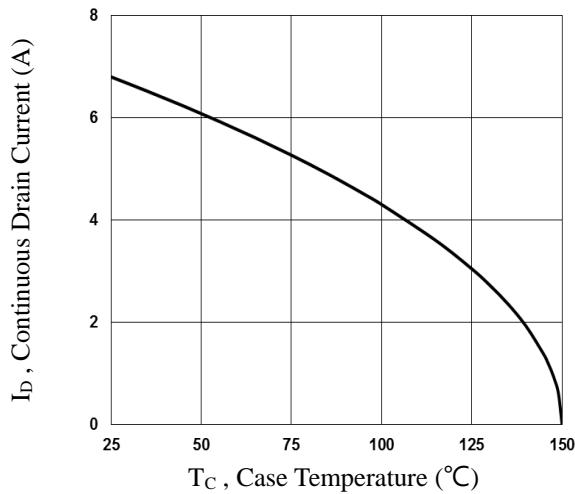
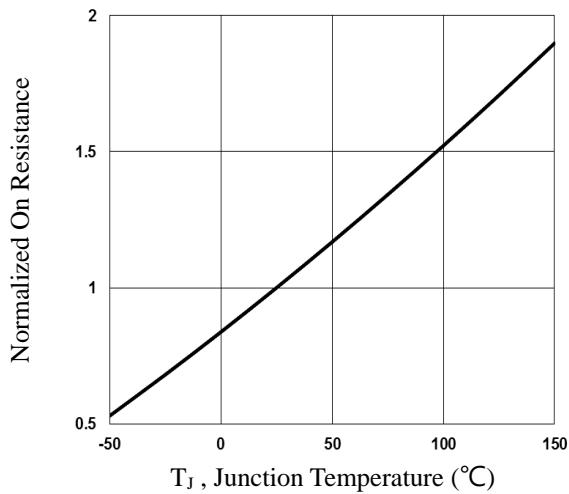
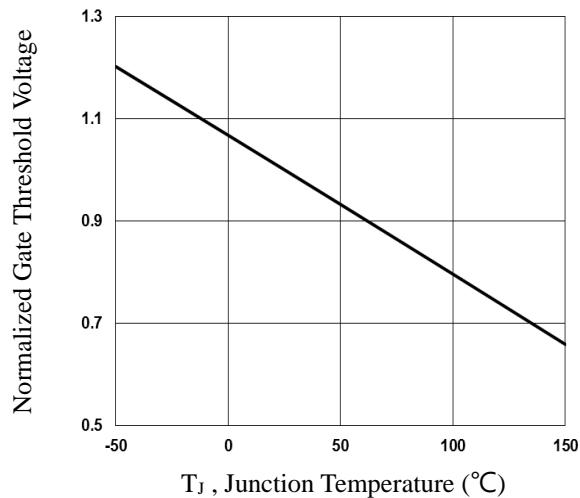
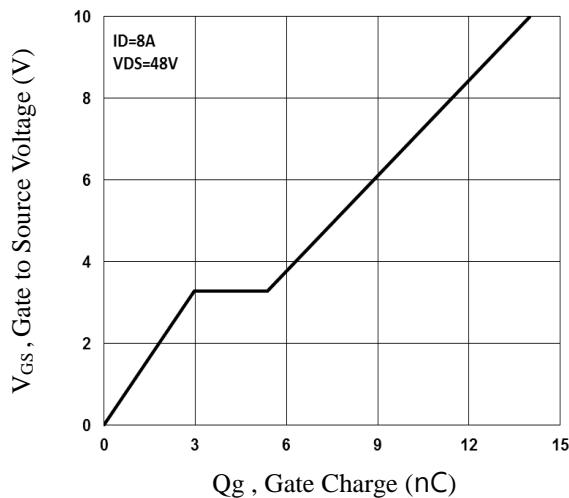
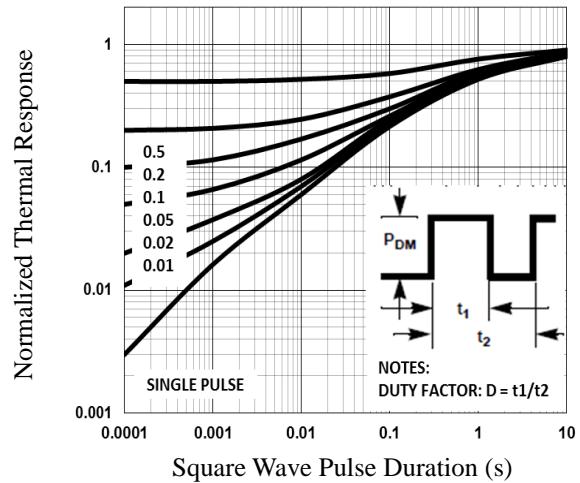
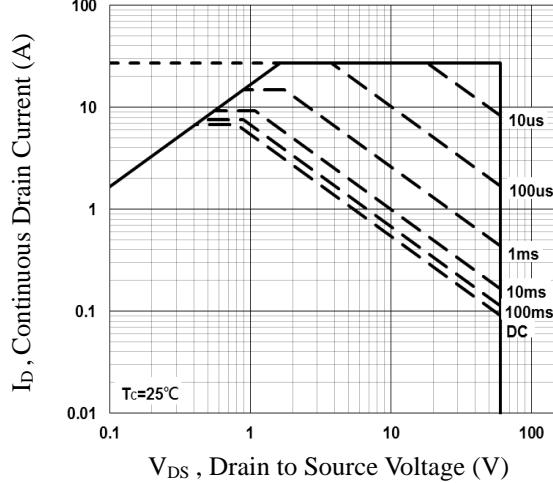
$Q_g$	Total Gate Charge <sup>2, 3</sup>	$V_{DS}=48\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=8\text{A}$	---	14	21	nC
$Q_{gs}$	Gate-Source Charge <sup>2, 3</sup>		---	2.9	5	
$Q_{gd}$	Gate-Drain Charge <sup>2, 3</sup>		---	2.4	4	
$T_{d(on)}$	Turn-On Delay Time <sup>2, 3</sup>	$V_{DD}=30\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=6\Omega$ $I_D=8\text{A}$	---	14	27	ns
$T_r$	Rise Time <sup>2, 3</sup>		---	4	8	
$T_{d(off)}$	Turn-Off Delay Time <sup>2, 3</sup>		---	32	60	
$T_f$	Fall Time <sup>2, 3</sup>		---	2	4	
$C_{iss}$	Input Capacitance	$V_{DS}=25\text{V}$ , $V_{GS}=0\text{V}$ , $F=1\text{MHz}$	---	835	1300	pF
$C_{oss}$	Output Capacitance		---	69	130	
$C_{rss}$	Reverse Transfer Capacitance		---	40	80	
$R_g$	Gate resistance	$V_{GS}=0\text{V}$ , $V_{DS}=0\text{V}$ , $F=1\text{MHz}$	---	1.7	3.4	$\Omega$

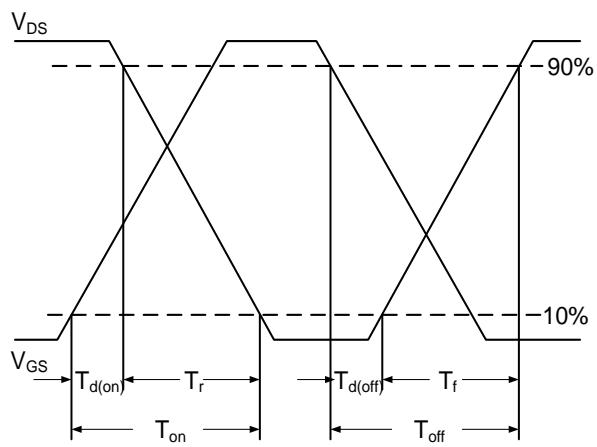
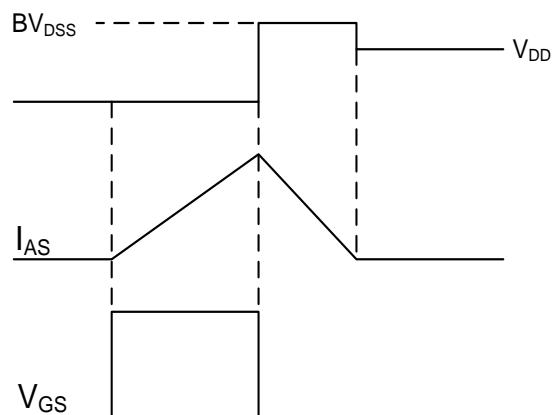
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	6.8	A
			---	---	13.6	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	V
$t_{rr}$	Reverse Recovery Time <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_s=-8\text{A}$ $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	14.6	---	ns
$Q_{rr}$	Reverse Recovery Charge <sup>2</sup>		---	6.6	---	nC

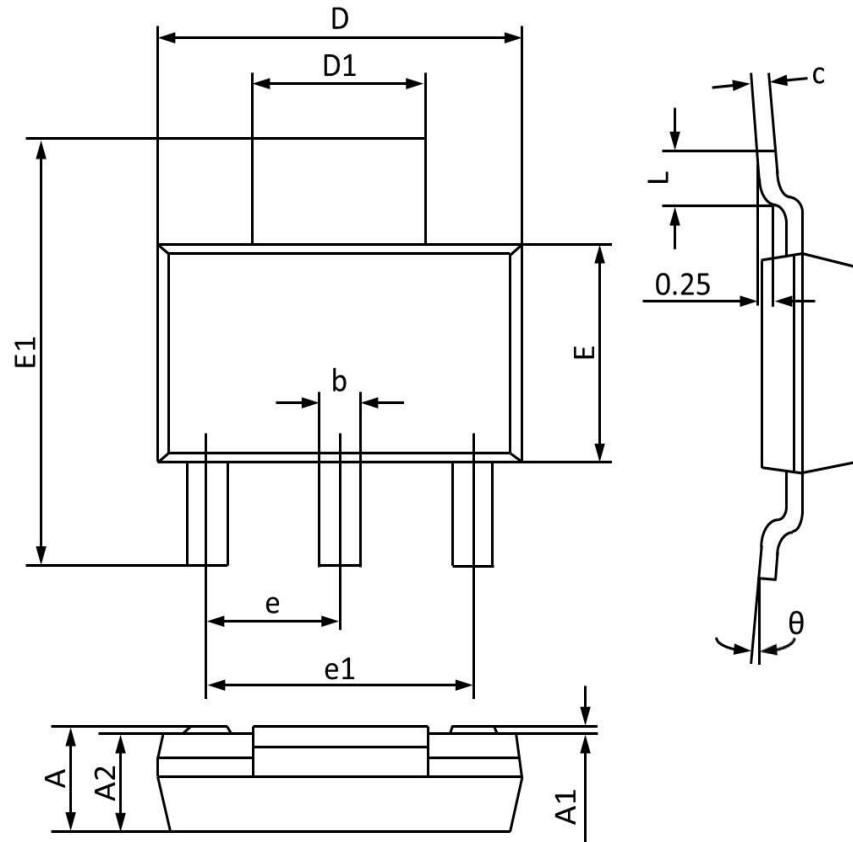
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25\text{V}$ ,  $V_{GS}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{AS}=15\text{A}$ , Starting  $T_J=25\text{ }^{\circ}\text{C}$
3. The data tested by pulsed , pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs.  $T_C$** 

**Fig.2 Normalized RD<sub>SON</sub> vs.  $T_J$** 

**Fig.3 Normalized  $V_{th}$  vs.  $T_J$** 

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Impedance**

**Fig.6 Maximum Safe Operation Area**


**Fig.7 Switching Time Waveform**

**Fig.8 EAS Waveform**

## SOT223 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.800	1.500	0.071	0.060
A1	0.120	0.000	0.005	0.000
A2	1.750	1.450	0.069	0.057
b	0.820	0.600	0.032	0.024
c	0.350	0.200	0.014	0.008
D	6.700	6.200	0.264	0.244
D1	3.100	2.900	0.122	0.114
E	3.700	3.300	0.146	0.130
E1	7.300	6.700	0.287	0.264
e	2.30(BSC)		0.091(BSC)	
e1	4.700	4.400	0.185	0.173
L	1.150	0.900	0.045	0.035
θ	10°	0°	10°	0°